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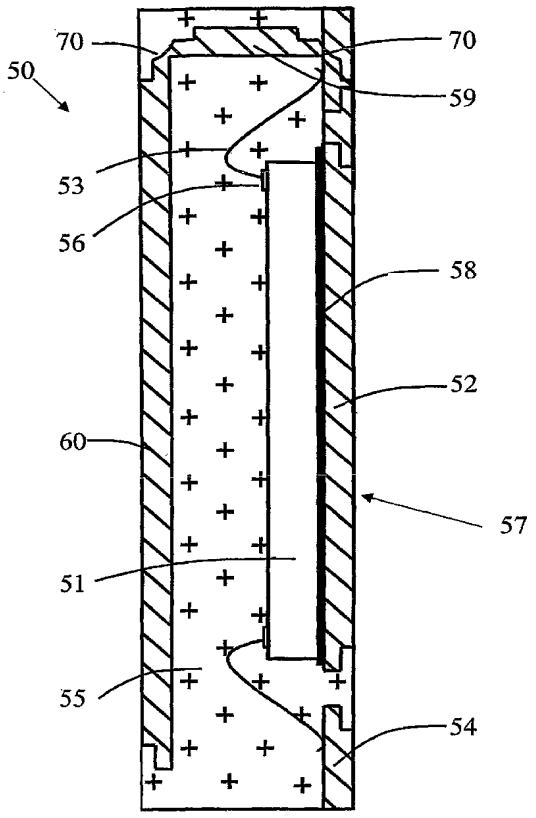
(54) Title: SEMICONDUCTOR PACKAGE WITH INTEGRATED HEATSINK AND ELECTROMAGNETIC SHIELD



(57) Abstract: The invention provides a mounting for a printed circuit board which mounting is suitable for receiving a semiconductor assembly wherein the mounting comprises: a base support having a semiconductor assembly facing surface, and an opposed printed surface board facing surface; a cover having a semiconductor assembly facing surface, an opposed heat radiating surface; a connecting formation which joins the cover to the base support and provides an electrical and thermal communication between the cover and the base support wherein the connecting formation has a semiconductor assembly facing surface, an outer opposed surface and a thickness between the two surfaces; and a plurality of package connectors extending from the base support each of which package connectors have a printed surface board facing surface; an array of mountings; and a semiconductor package comprising a semiconductor assembly having one or more semiconductor chips, which assembly is mounted on the mounting wherein the package connectors of the mounting are in a spaced relationship with the base support and are linked electrically with the semiconductor assembly and the cover is arranged to be in a spaced parallel relationship with the base support.

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